

1 ABSTRACT OF THE DISCLOSURE UNDER 37 C.F.R. §1.72(b)

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3 Selective application of solder bumps in an integrated circuit package.
4 Solder bumps are selectively applied in a solder bump integrated circuit
5 packaging process so that portions of a circuit can be effectively disabled.
6 The bumps may be selectively applied either to a die or to the substrate using
7 multiple solder masks, one for each pattern of solder bumps desired or can be
8 otherwise applied in multiple patterns depending upon which portions of the
9 circuitry are to be active and which are to be disabled.

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